

PCB Material	Breakdown Voltage	CTI Value	Board Thickness (mm)	Copper Thickness	Thermal Conductivity W/mK	Surface Treatment	Technology
MCPCB	3KV	>=600V	0,80/ 1,00 /1,20/ 1,60 /2,00/3,00	18µm- 35µm -70µm-105µm (H Oz- 1 Oz -2 Oz-3 Oz)	1.00-2.00	LFHAL HASL OSP IMMERSION TIN IMMERSION GOLD HARD GOLD IMMERSION SILVER	Printing / Exposure
FR4	>=20KV	>=175V	0,80/ 1,00 / 1,20 / 1,60 /2,00/3,00		0.5-1.00		

*Specifications with bold character are widely used.

Panel Size		V-Cut, Router, Punch	Solder Mask Thickness	Solder Mask	Silkscreen	Laminate	E-Test
FR4 1.2	1041*1245mm (2 layer)	✓	8-13µm	White Black Red Green Blue Matte Black Super White	Grey White Black Red Blue	1060/ 5052 Alloy	40V,100V,250V 10Q-25MΩ
FR4 1.6	1041*1245mm						
FR4 1.6 2L	1041*1245mm, 940*1245mm, 1041*1252mm						
MCPCB 1.6 1 Oz 1W/mK	1000*1200mm						
MCPCB 1.6 1 Oz 1.5W/mK							
MCPCB 1.6 1 Oz 2W/mK							
MCPCB 1.6 1 Oz 2.5W/mK							
	500*1200mm	TG130/ TG 150 / TG 170					

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